VieTape TIM9001

HIGH THERMALLY CONDUCTIVE GAP FILLER PAD

DESCRIPTION

VieTape TIM9001 is high conductive pad designed with low thermal resistance and excellent electrical insulation. It provides good performance at low compression and highly stable at a wide range of temperature (-40°C~150°C).

APPLICATION

Electric Vehicles, 5G, Autopilot System, Mobile Phone, AIOT, HPC (High Performance Computing), Server, IC, CPU, MOS, LED, Mother Board, Power Supply, Heat Sink, LCD-TV, Notebook, PC, Telecom Device, Wireless Hub, DDR II Module, ...

TYPICAL PERFORMANCE PROPERTIES

PROPERTIES	VALUE	METHOD
Appearance	Green	-
Thickness	0.5-6.0 mm	ASTM D374
Density	3.1- 3.3 g/cm^3	ASTM D792
Weight loss	≤ 1.0%	ASTM E595
Hardness	40 shore 00	ASTM D2240
Breakdown Voltage	>5.0 kV/mm	ASTM D149
Volume Resistivity	10^{10} Ohm-cm	ASTM D257
Dielectric Constant@1MHz	7.0	ASTM D150
Thermal conductivity	5.0 W/m.K	ISO22007-2
Thermal resistance	0.31 ^{0}C.in^2/W	ASTM D5470
Working Temperature	-40 - 150^{0}C	-

SHELF LIFE AND STORAGE

12 months from date of manufacture when stored at 10-30°C and 40 - 50% relative humidity. Avoid high humidity and exposure to sunlight.

CAUTION

For safe handling information on this product, please review the Safety Data Sheet, SDS

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